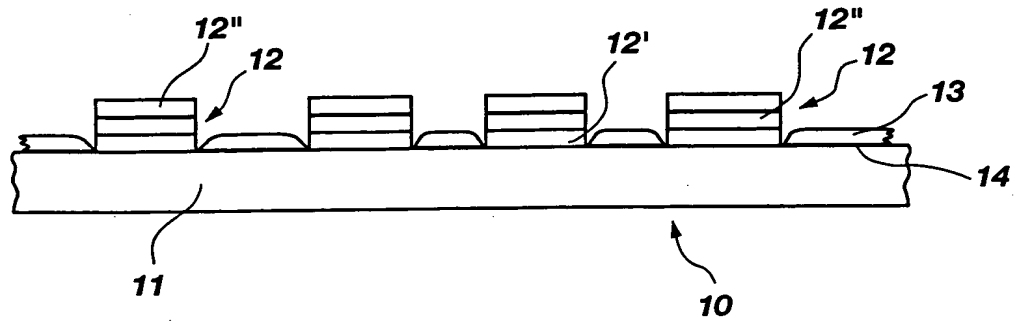


TITLE: METHOD OF IMPROVING COPPER INTERCONNECTS OF  
SEMICONDUCTOR DEVICES FOR BONDING

Inventor: Salman Akram

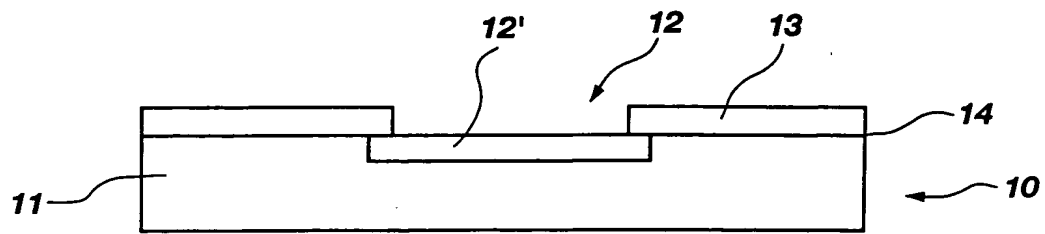
Docket No.: 3854.3US

1/17

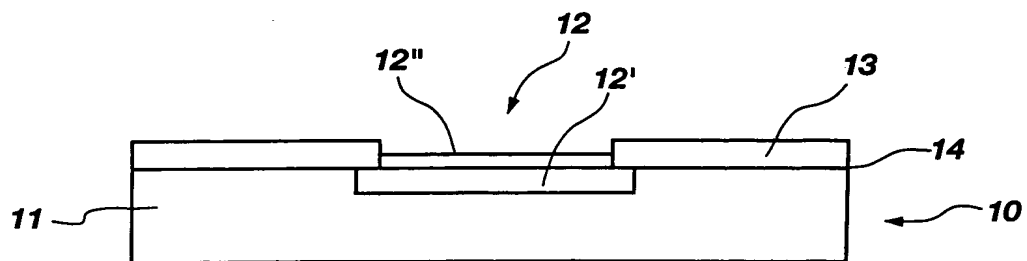


**Fig. 1**

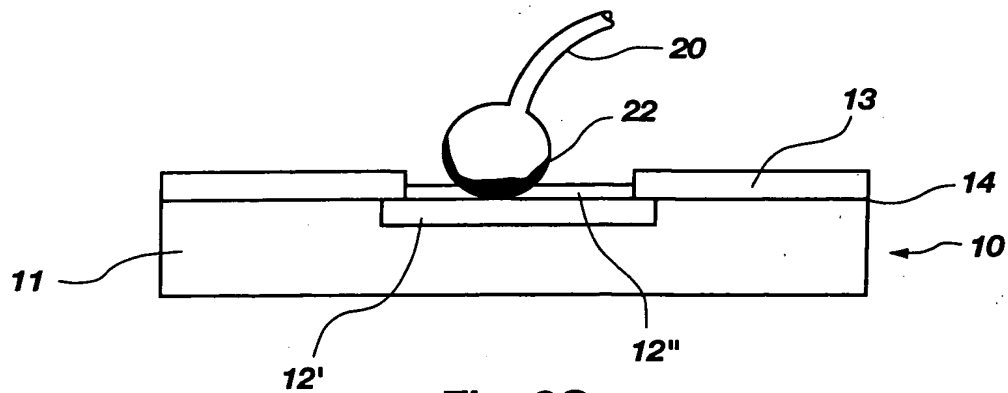
2/17



**Fig. 2A**

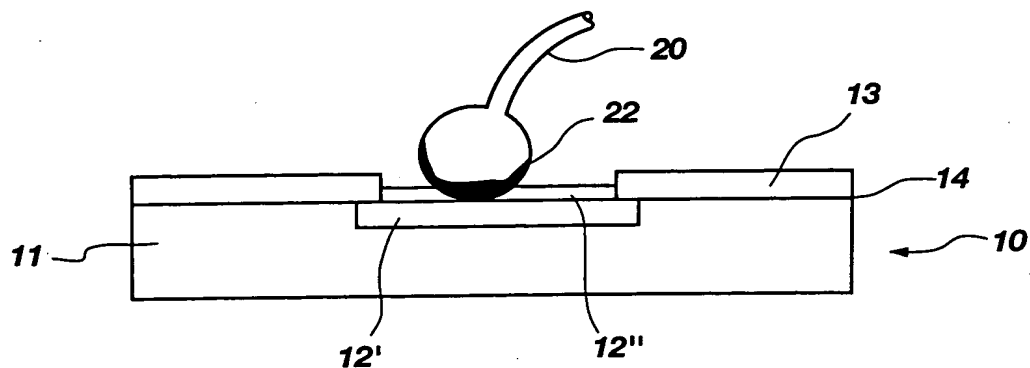


**Fig. 2B**

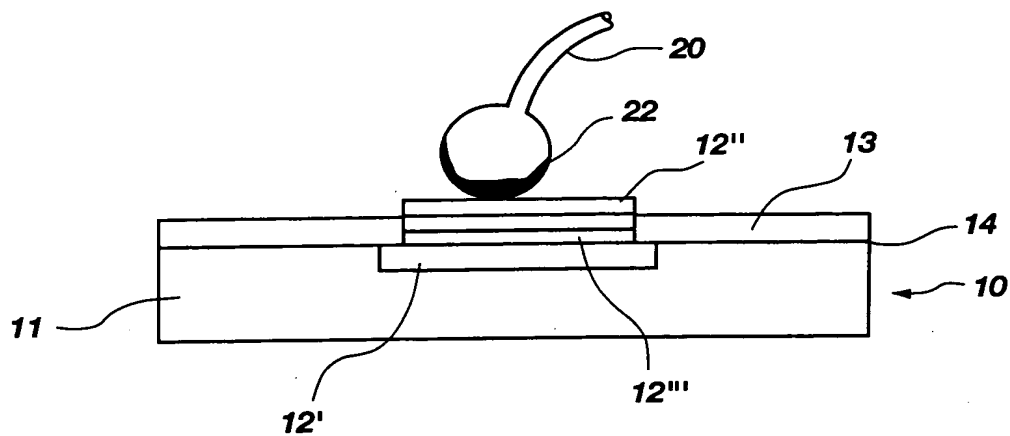


**Fig. 2C**

3/17

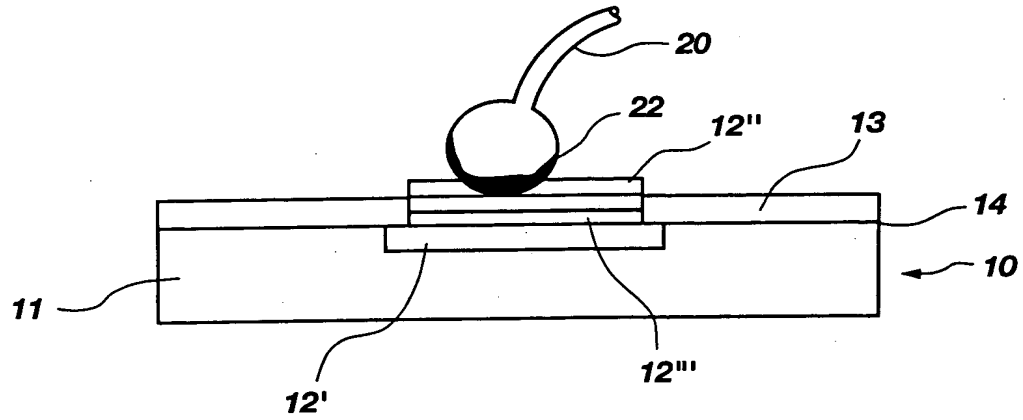


**Fig. 2D**

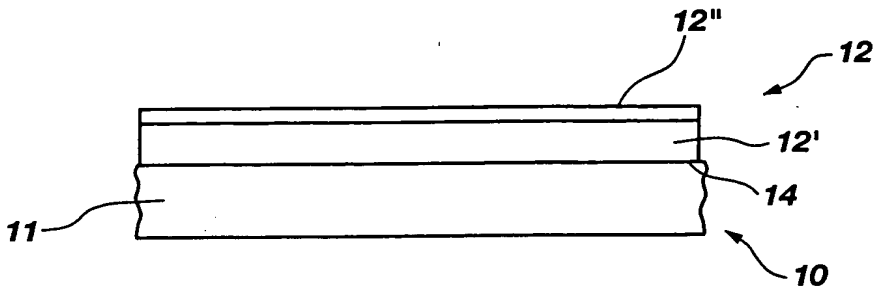


**Fig. 2E**

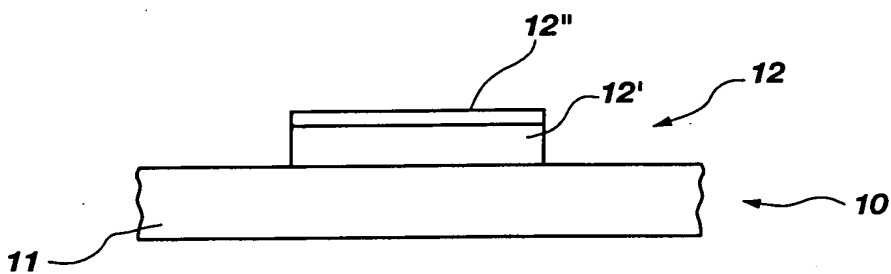
4/17



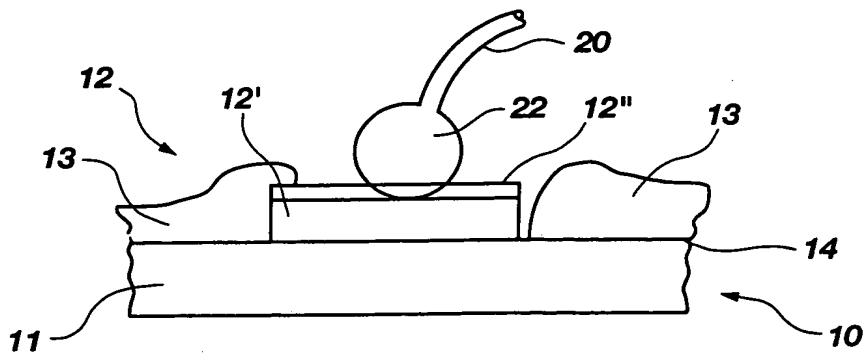
**Fig. 2F**



**Fig. 3A**

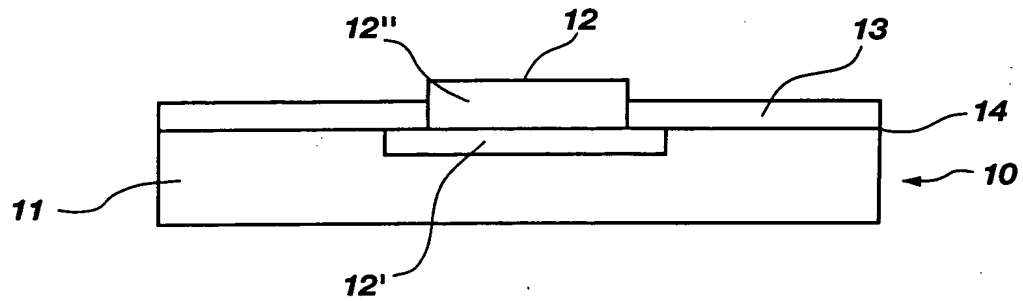


**Fig. 3B**

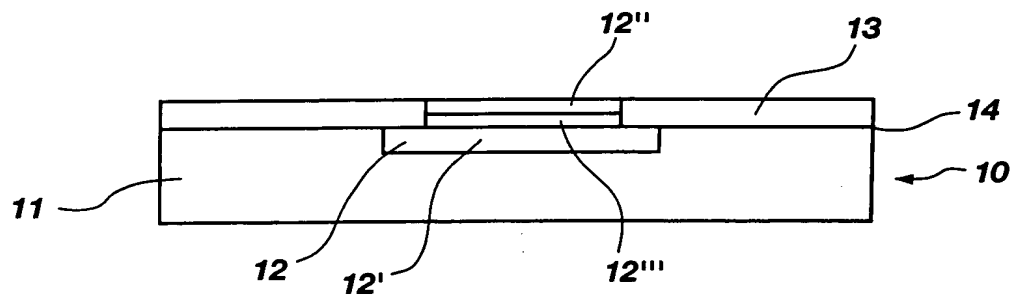


**Fig. 3C**

6/17



**Fig. 4A**

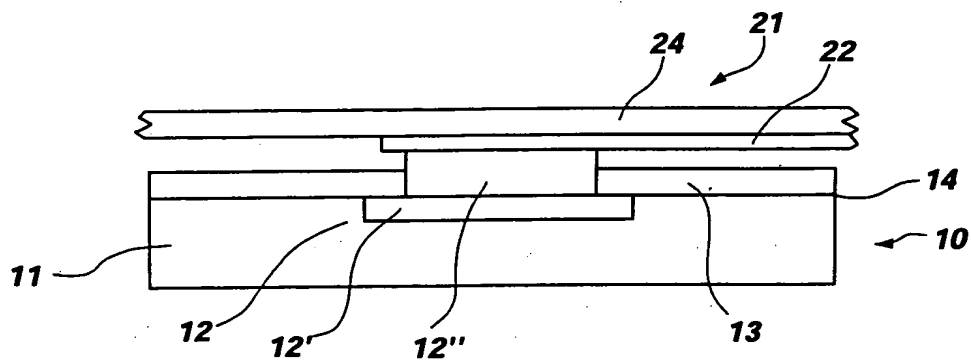


**Fig. 4B**

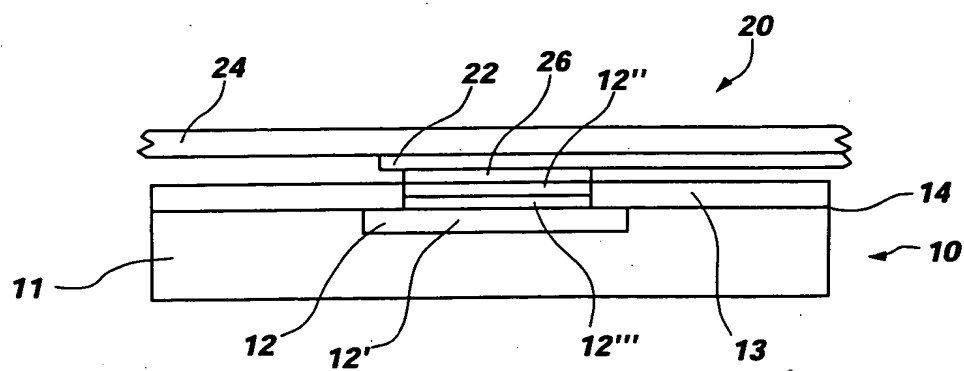
TITLE: METHOD OF IMPROVING COPPER INTERCONNECTS OF  
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7/17

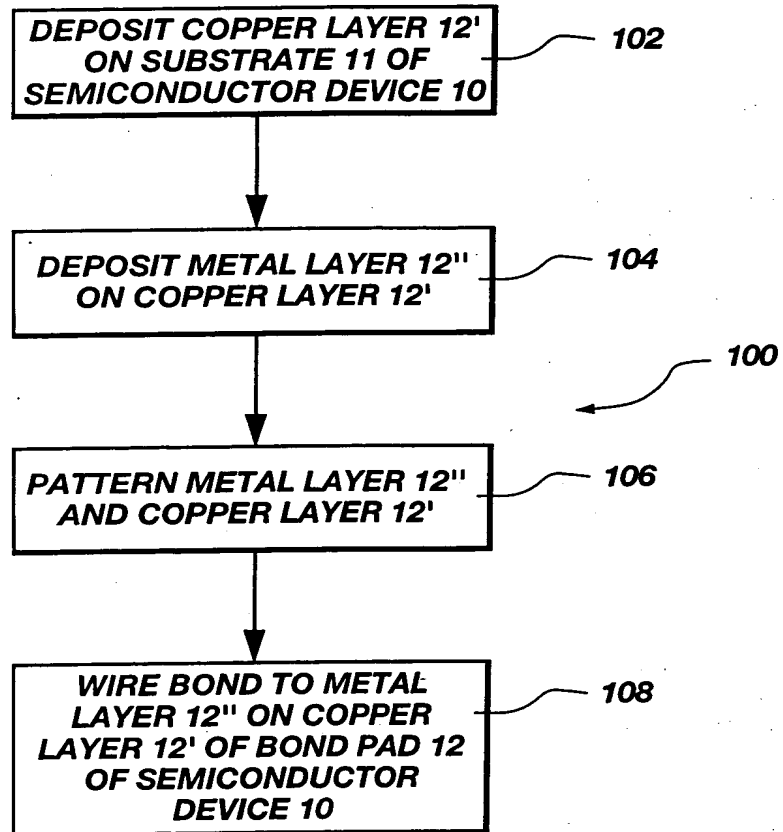


**Fig. 4C**



**Fig. 4D**

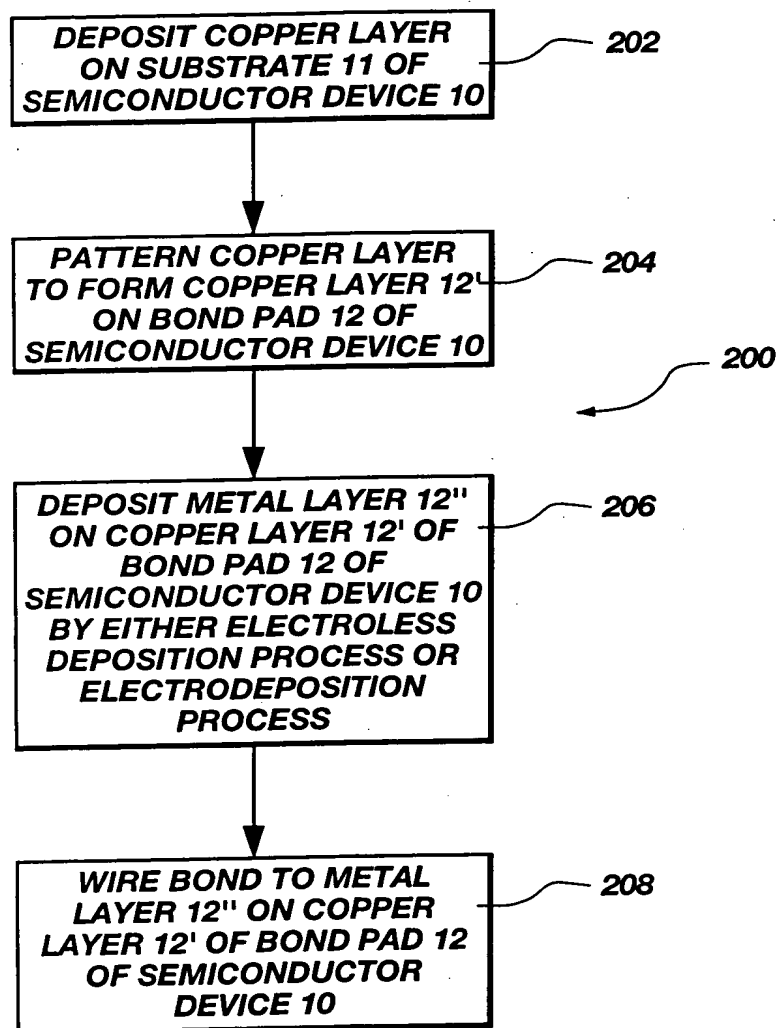
8/17



**Fig. 5A**

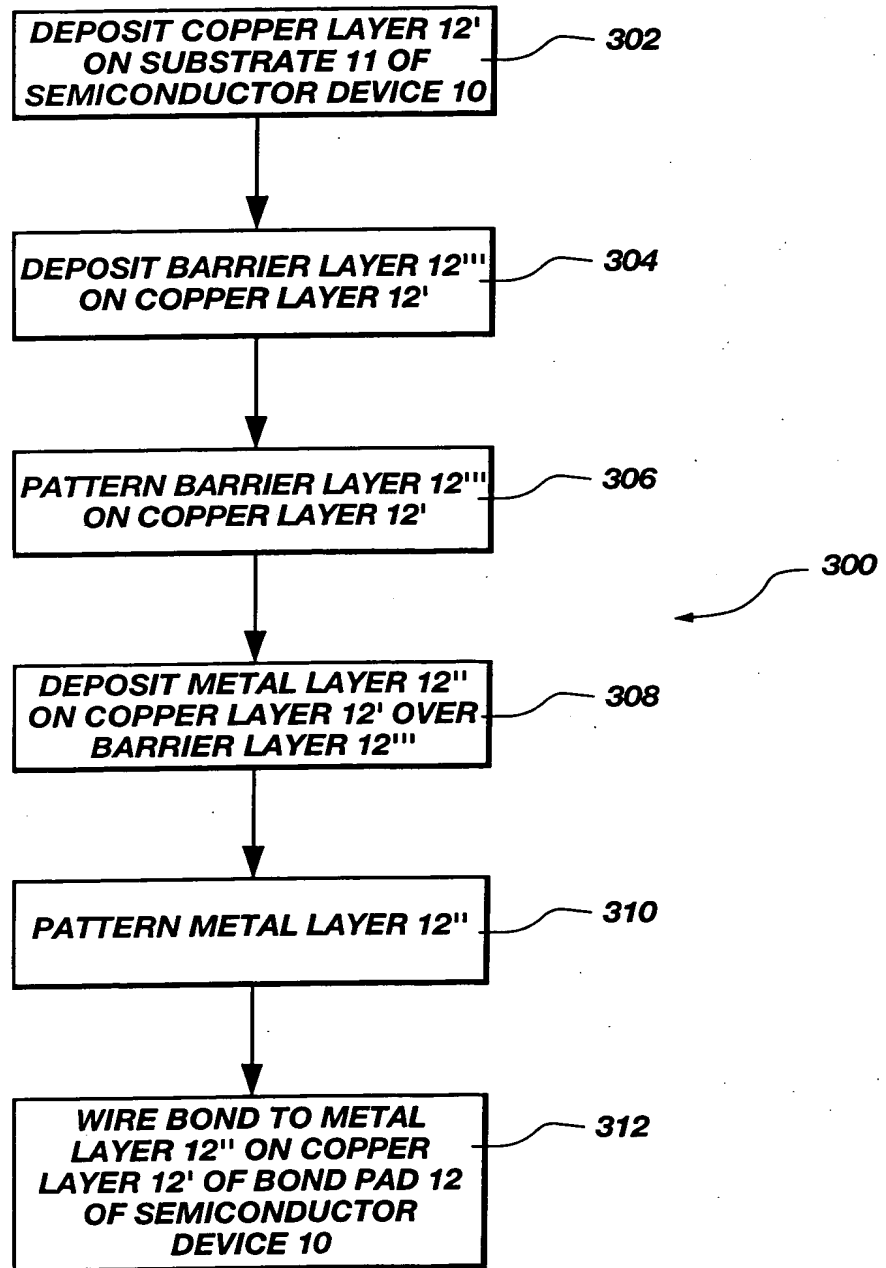


9/17



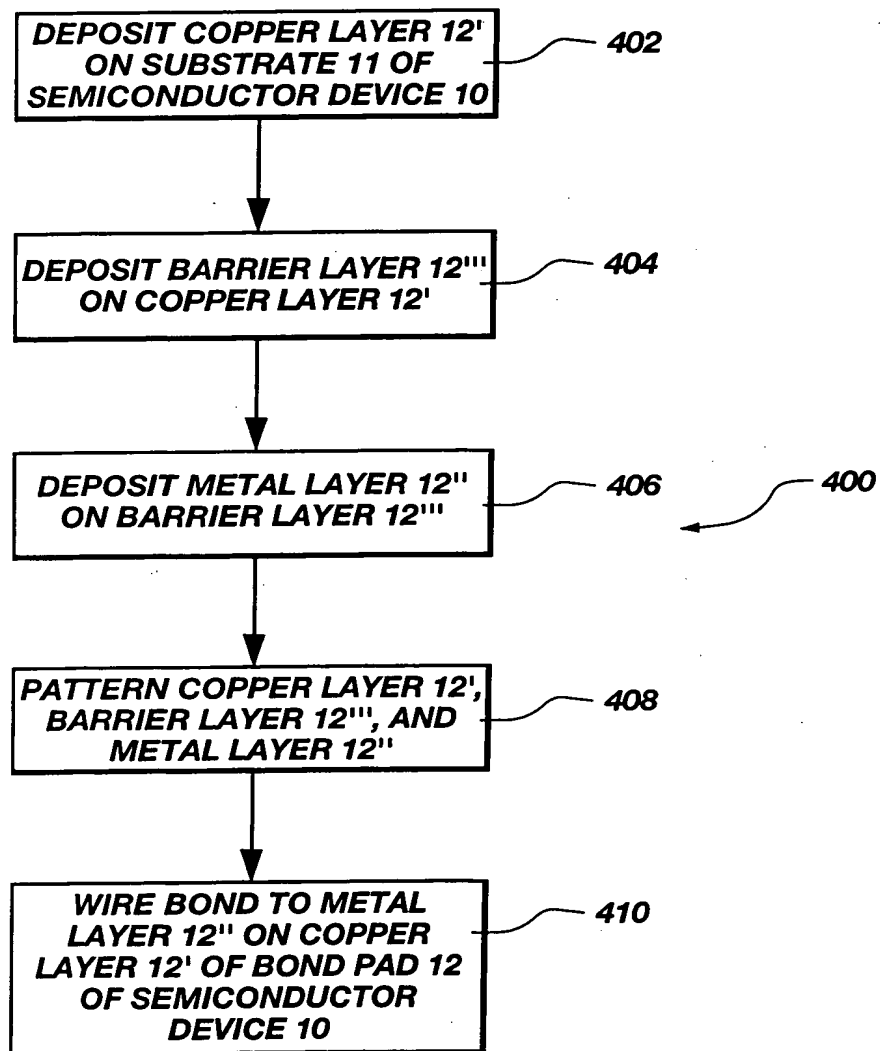
**Fig. 5B**

10/17



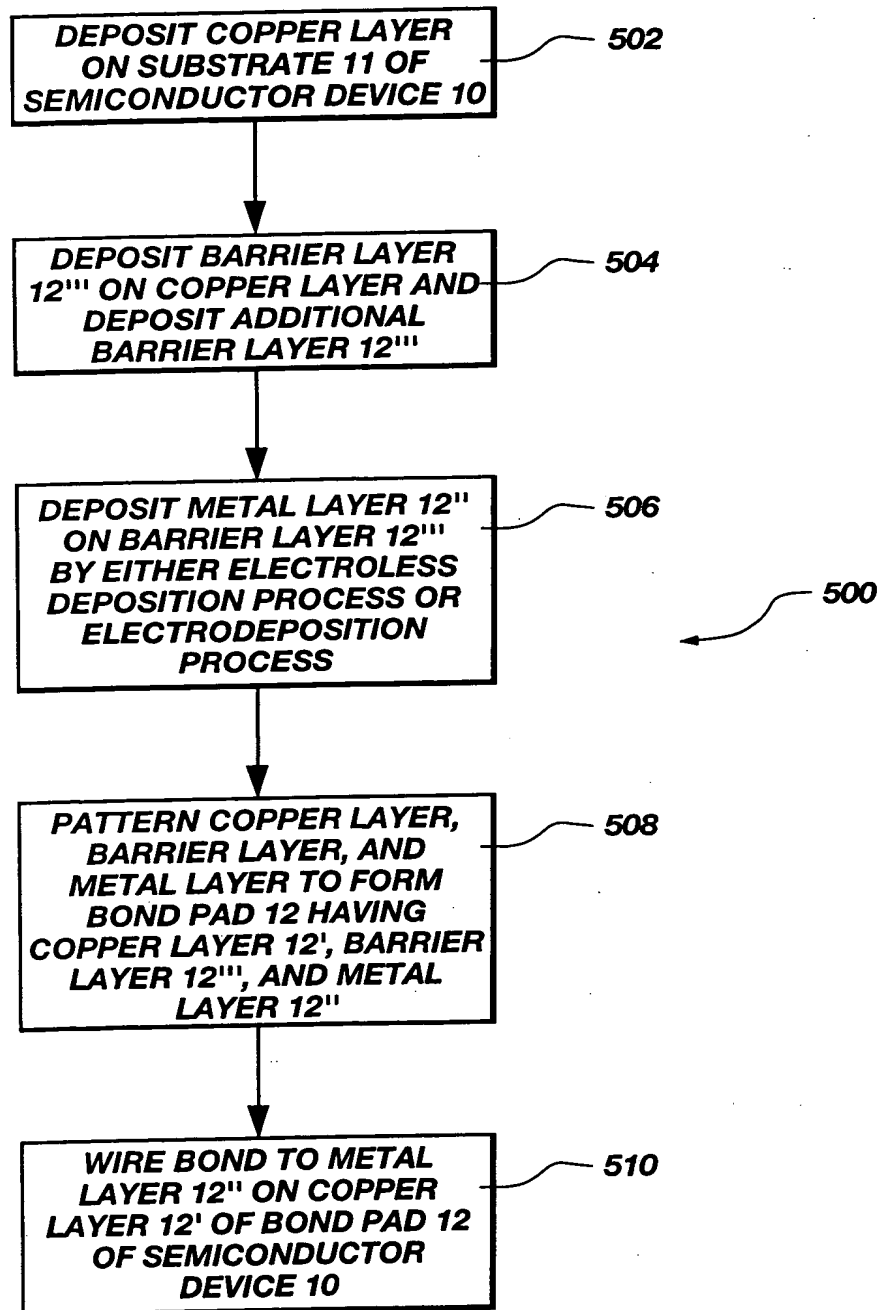
**Fig. 5C**

11/17



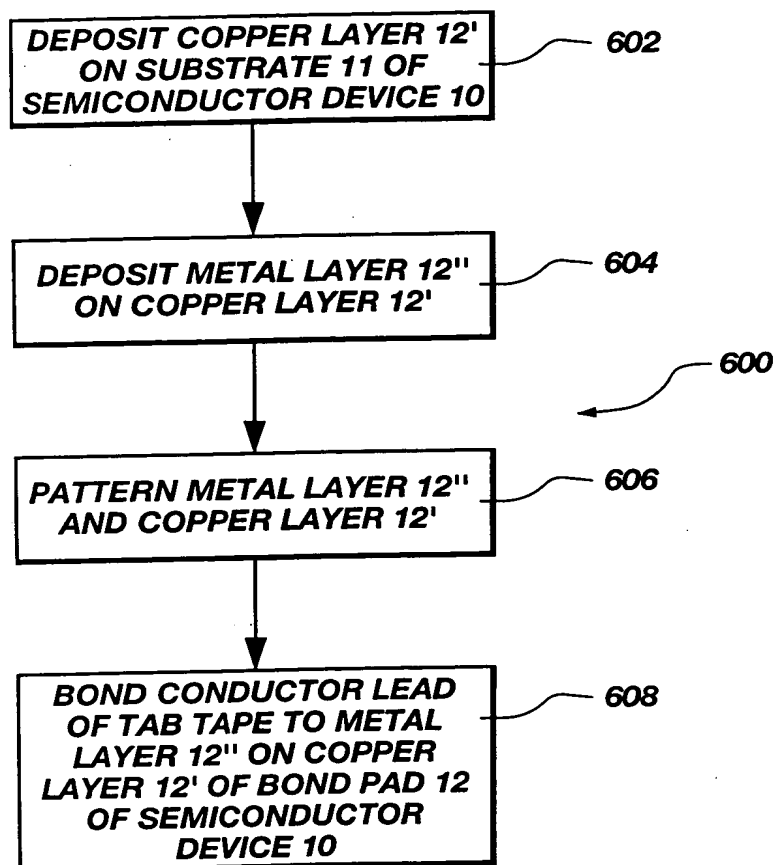
**Fig. 5D**

12/17



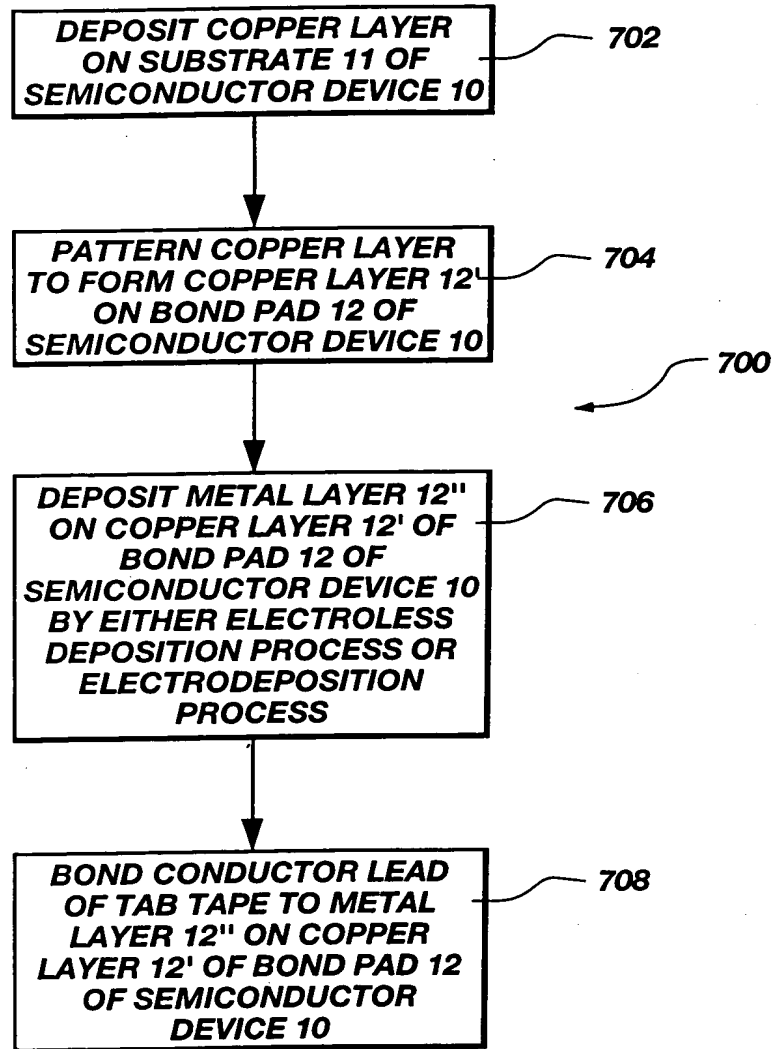
**Fig. 5E**

13/17



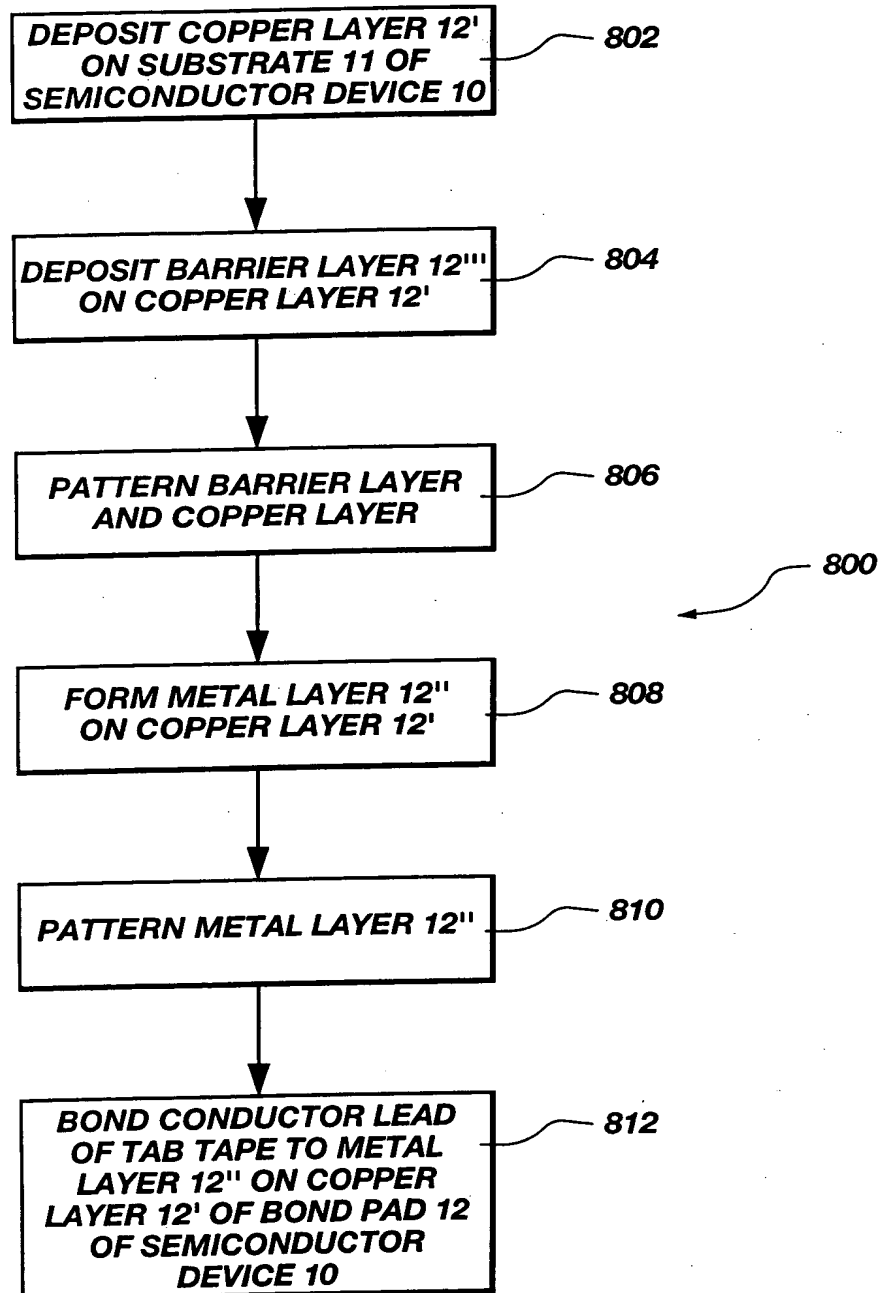
**Fig. 5F**

14/17



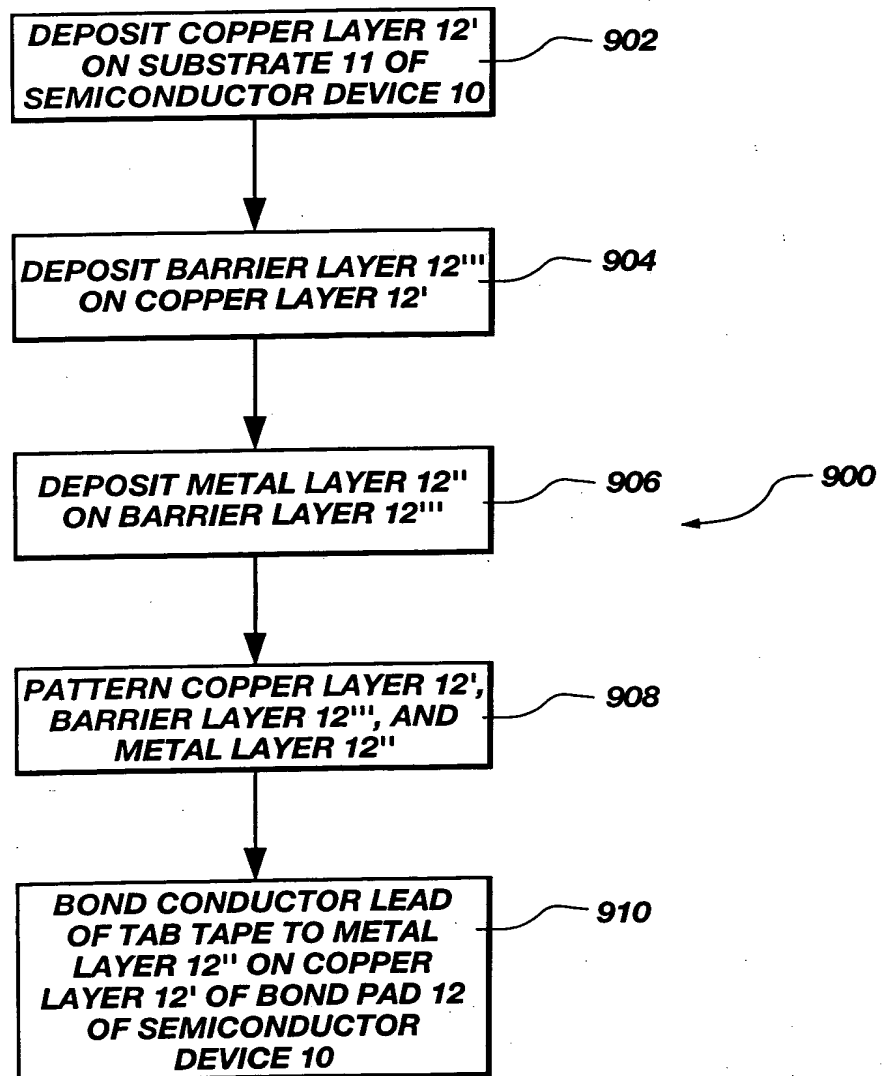
**Fig. 5G**

15/17



**Fig. 5H**

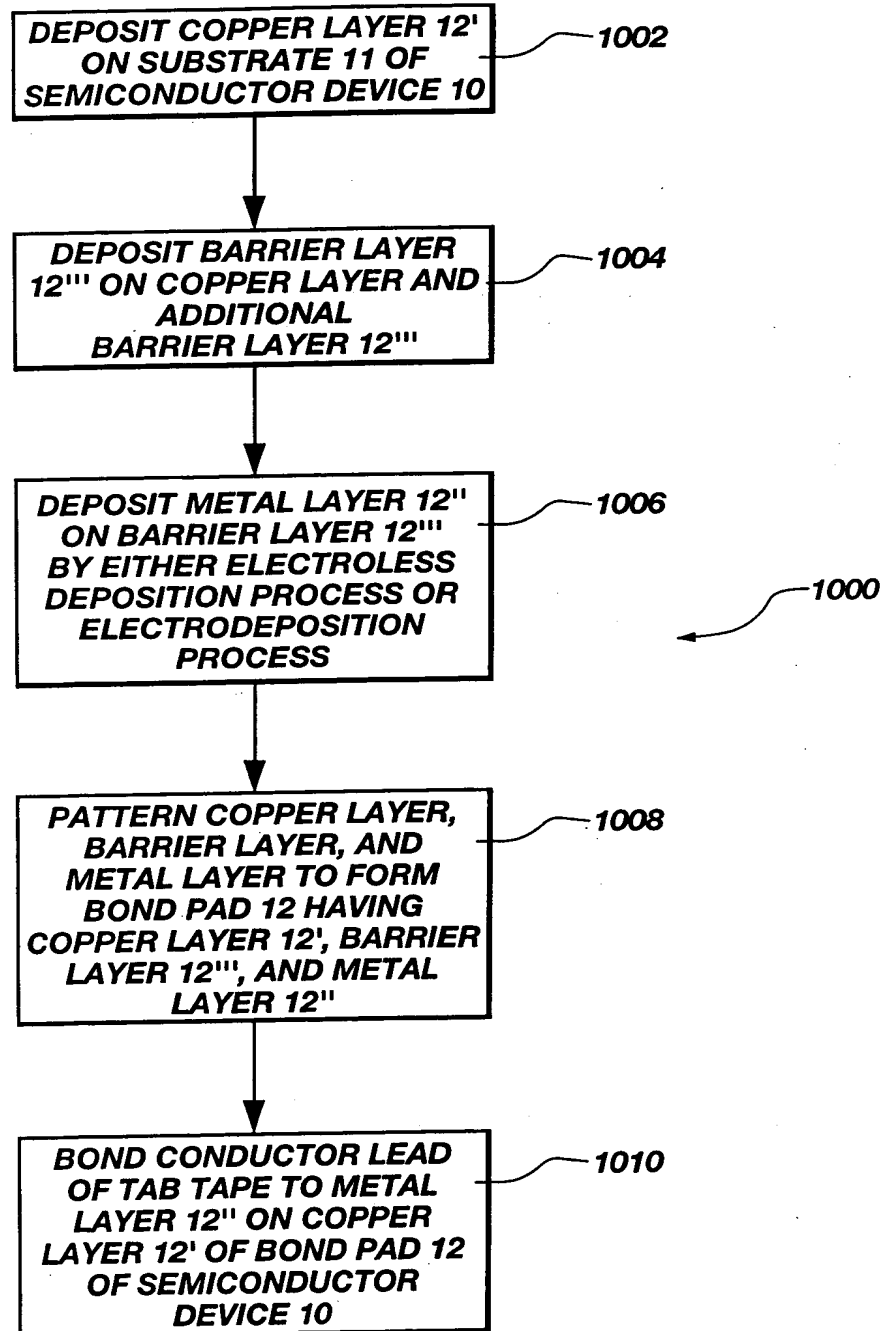
16/17



**Fig. 5I**



17/17



**Fig. 5J**